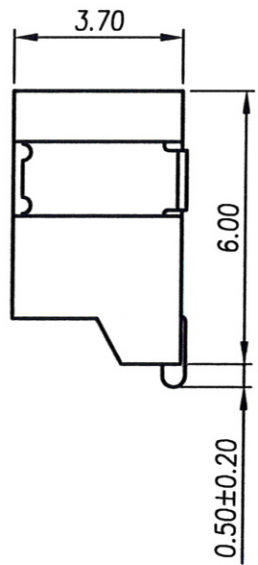
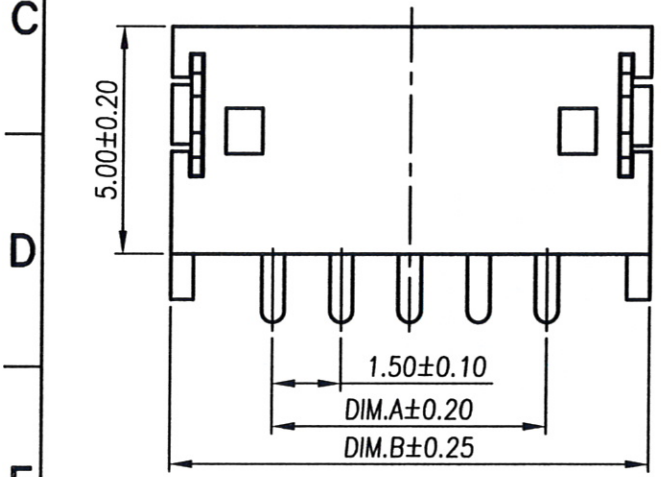
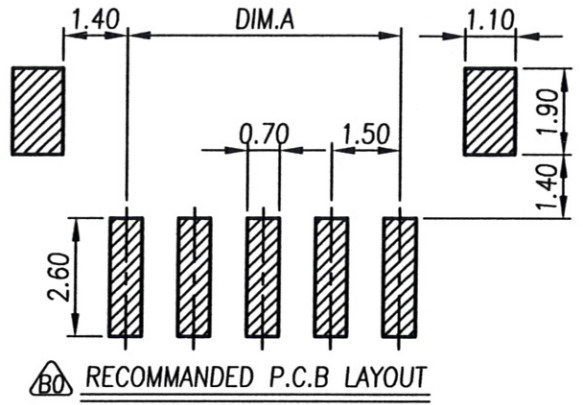
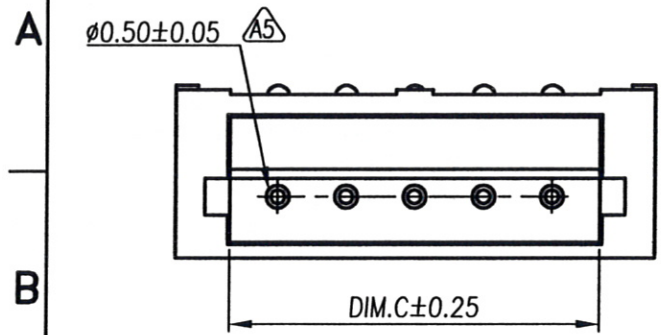


RoHS Compliant

| REV | MODIFICATION | DATE | DRAW |
|-----|------------------------|------------|----------|
| A4 | Release To ECN20120506 | 2012.05.17 | Seven |
| A5 | Release To ECN20130203 | 2013.02.20 | Seven |
| B0 | Release To ECN20141206 | 2014.12.24 | Michelle |



Specification

- 1.Current Rating&Voltage Rating:1A & 100V AC/DC
- 2.Contact Resistance:20mΩ Maximum
- 3.Insulation Resistance:500MΩ Minimum At DC 500V
- 4.Dielectric Withstanding Voltage:AC500V/Minute
- 5.Operating Temperature:-25°C~+85°C

△ B0

Material:

- 1.Housing:High Temperature Thermoplastic UL94V-0
- 2.Tab:Copper Alloy T=0.25mm
- 3.Contact Pin:Copper Alloy Ø0.50mm

△ B0

Finish:

- 1.Housing:Nature
- 2.Tab:Tin Plated Over Nickel
- 3.Contact Pin:Tin Plated Over Nickel

Part No.: AS06601 XX X X X 2

Number of Pin 02~13

Housing Material

△ B0

A:HTN UL94V-0 Nature H.F

B:NY9T UL94V-0 Nature


Plating

- 1:Tab:Bright Tin Plated Over Nickel
PIN:Bright Tin Plated Over Nickel
- 2:Tab:Bright Tin Plated Over Nickel
PIN:Matte Tin Plated Over Nickel

Packing
1:T&R
4:TUBE



| PIN | DIM.A | DIM.B | DIM.C | PIN | DIM.A | DIM.B | DIM.C |
|-----|-------|-------|-------|-----|-------|-------|-------|
| 02 | 1.50 | 6.00 | 3.60 | 08 | 10.50 | 15.00 | 12.60 |
| 03 | 3.00 | 7.50 | 5.10 | 09 | 12.00 | 16.50 | 14.10 |
| 04 | 4.50 | 9.00 | 6.60 | 10 | 13.50 | 18.00 | 15.60 |
| 05 | 6.00 | 10.50 | 8.10 | 11 | 15.00 | 19.50 | 17.10 |
| 06 | 7.50 | 12.00 | 9.60 | 12 | 16.50 | 21.00 | 18.60 |
| 07 | 9.00 | 13.50 | 11.10 | 13 | 18.00 | 22.50 | 20.10 |



金上達科技股份有限公司

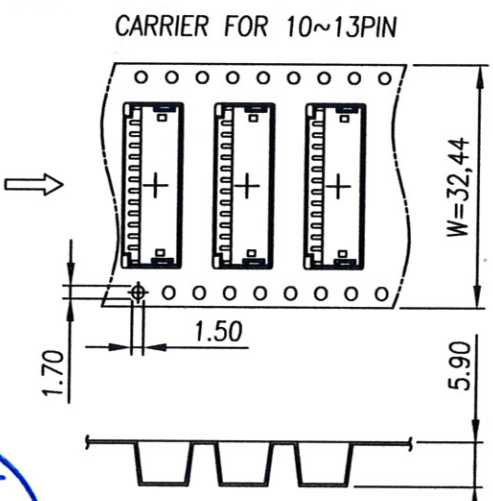
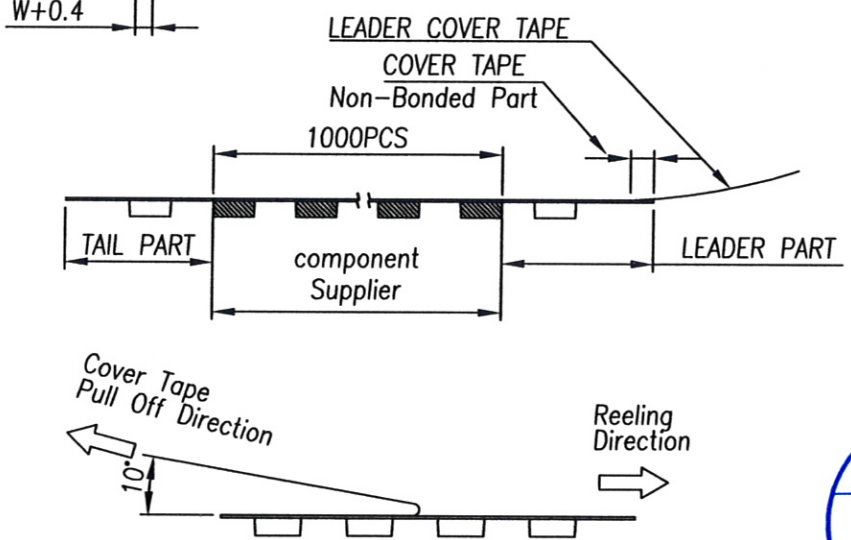
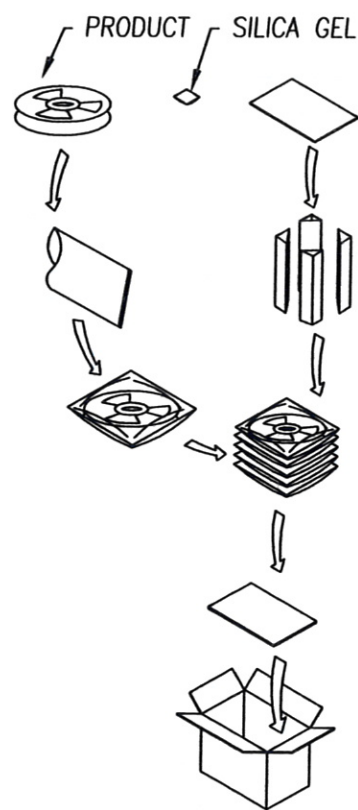
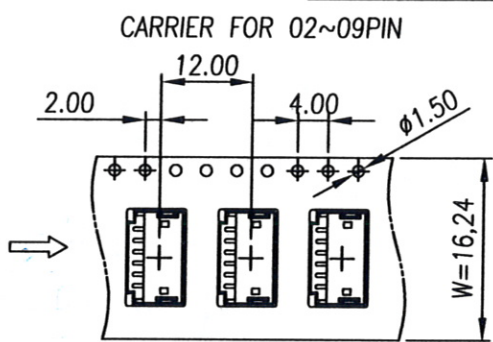
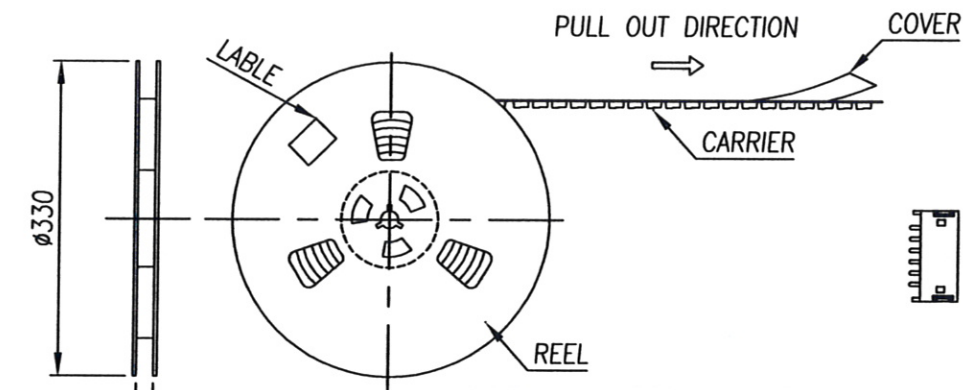
GOLDENSUNDA TECHNOLOGY CO.,LTD

| | | |
|--------------------------------------|-----------------------|---|
| TOLERANCE UNLESS OTHERWISE SPECIFIED | | PROJ. TITLE: Wire To Board Wafer 1.50mm 90° SMT Single Row |
| .x± 0.35 | x.* 2' | APR. C.F.Liao 20141224 |
| .xx± 0.25 | .*x± 1' | CHK. Abel 20141224 |
| .xxx± 0.15 | .xx.*± 0.5' | DRA. Michelle 20141224 |
| PART NO. AS06601XXXXX2 | DWG NO. AS06601XXXXX2 | |
| UNITS: mm | CUSTOMER DRAWING | |
| SIZE: A4 | SCALE: 6:1 | SHEET 1 / 2 |
| REV B0 | V | |

RoHS Compliant



| REV | MODIFICATION | DATE | DRAW |
|-----|------------------------|------------|----------|
| A4 | Release To ECN20120506 | 2012.05.17 | Seven |
| A5 | Release To ECN20130203 | 2013.02.20 | Seven |
| B0 | Release To ECN20141206 | 2014.12.24 | Michelle |



發行
103.12.24
文管中心

| NO. OF PIN | W±0.3 | PCS / REEL |
|------------|-------|------------|
| 02 ~ 04 | 16 | 1000 |
| 05 ~ 09 | 24 | |
| 10 | 32 | |
| 11 ~ 13 | 44 | |

NOTES:
1. Material : PS
2. Part No.: AS06601XXXX12

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GOLDENSUNDA TECHNOLOGY CO.,LTD

| | | | | |
|--------------------------------------|------------|----------------------------|--|---------------------------------|
| TOLERANCE UNLESS OTHERWISE SPECIFIED | | PROJ. | TITLE: Wire To Board Wafer 1.50mm 90° SMT Single Row | |
| .x± 0.35 | .x'± 2' | APR. C.F.Liao 20141224 | PART NO. AS06601XXXXX2 | DWG NO. AS06601XXXXX2 |
| .xx± 0.25 | .x'± 1' | CHK. Abel 20141224 | UNITS: mm | CUSTOMER DRAWING |
| .xxx± 0.15 | .xx'± 0.5' | DRAW. Michelle 20141224 | SIZE: A4 | SCALE FREE SHEET 2 / 2 REV B0 V |